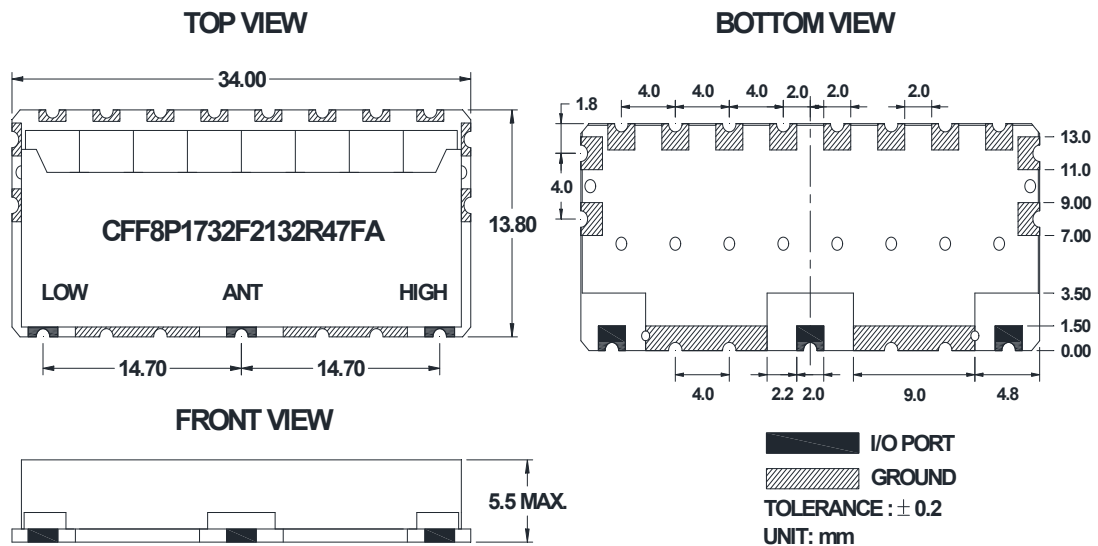


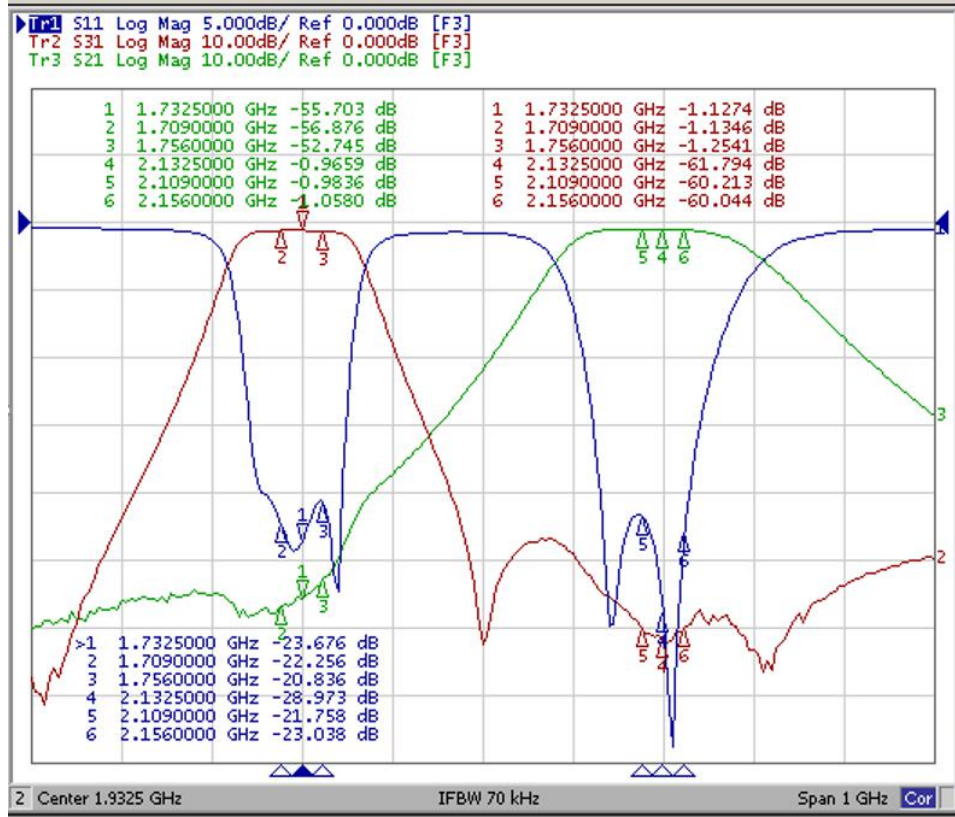
Electrical Specification

ITEMS	ANT>>LOW	ANT>>High	UNIT
Center Frequency [fo]	1732.5	2132.5	MHz
Bandwidth [BW]	fo ±23.5 [1709 ~ 1756]	fo ±23.5 [2109~2156]	MHz
Insertion Loss in BW	1.6	1.6	dB max
Ripple in BW	0.5	0.5	dB max
Return Loss in BW <input checked="" type="checkbox"/> ANT Port	15	15	dB min
VSW Rin BW <input checked="" type="checkbox"/> ALL Port			max
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	35dBc min @ [2109~2156]	35dBc min @ [1709~1756]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
	dB min @ fo ± [~]	dB min @ fo ± [~]	MHz
Isolations	dB min@[~]		MHz
	dB min@[~]		MHz
Input Power	3		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

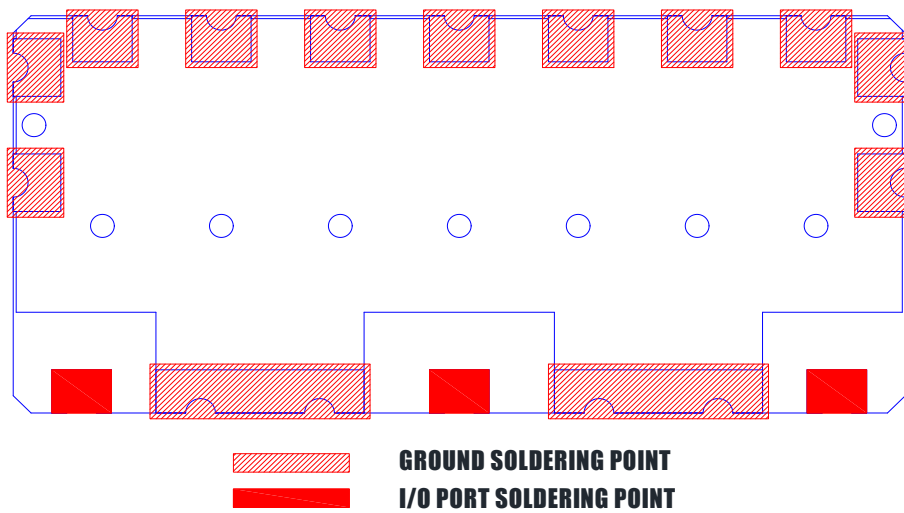
Mechanical Specification



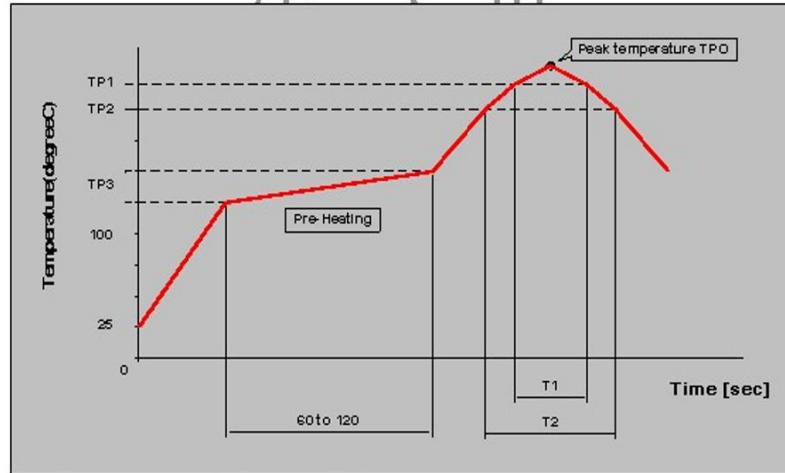
Plot Data



Recommended PC Board Pattern



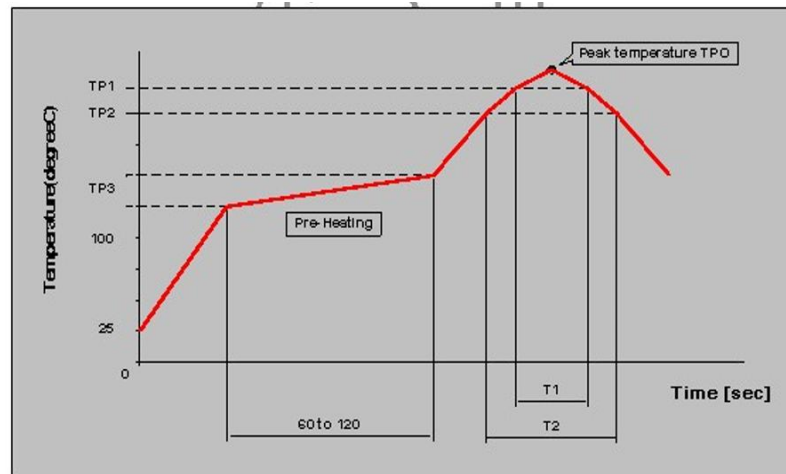
Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±1.5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180



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